Product/Process Change Notice - PCN 26_0039 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. An acceptance or concern response should be submitted to ADI promptly. Any requests for samples of changed material or additional information must be made within 30 days of the notification. In accordance with JEDEC Standard 046, customers should acknowledge receipt of the PCN within 30 days of the PCN delivery. ADI contact information is listed below. Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change. After the acknowledgment, a lack of additional requests within 90 days constitutes acceptance of the change.

PCN Title:	Qualification of Wafer Fabrication Site Analog Devices Limerick for XFCB Products
Publication Date:	31-Mar-2026
Effectivity Date:	03-Jul-2026 *(the earliest date that a customer could expect to receive changed material)*
Revision Description:	Initial Release.

Description Of Change:

Qualification of Analog Devices International, Ireland (ADLK) as a wafer fab site for XFCB products.

Reason For Change:

Leveraging the existing qualified process at our Analog Devices Limerick, Ireland Fab ensures a reliable and continuous supply for our customers securing their needs well into the future.

The affected products will be manufactured using ADI specified manufacturing flows, materials, process controls, and monitors ensuring no degradation of quality and reliability performance.

Impact of the change (positive or negative) on fit, form, function & reliability:

There is no impact to fit, form, function, or reliability.

Product Identification: *(this section will describe how to identify the changed material)*

Traceability will be maintained via standard ADI lot traceability.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents:

Attachment 1: Type: Qualification Results Summary

ADI_PCN_26_0039_Rev_-_Qualification_of_ADI_Limerick_Wafer_Fab_XFCB_Processes.pdf

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

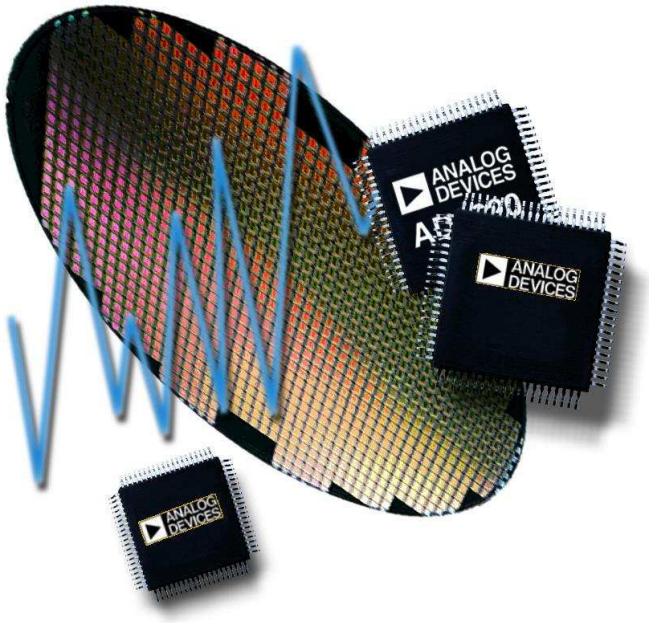
Americas:	Europe:	Japan:	Korea:	Rest of Asia:

Appendix A - Affected ADI Models:

Added Parts On This Revision - Product Family / Model Number (129)

AD604 / AD604ARSZ	AD604 / AD604ARSZ-R7	AD604 / AD604ARZ	AD604 / AD604ARZ-RL	AD607 / AD607ARSZ
AD607 / AD607ARSZ-REEL	AD8009 / AD8009ACHIPS	AD8009 / AD8009ARZ	AD8009 / AD8009ARZ-REEL	AD8009 / AD8009ARZ-REEL7
AD8009 / AD8009JRTZ-REEL	AD8009 / AD8009JRTZ-REEL7	AD8011 / AD8011ANZ	AD8011 / AD8011ARZ	AD8011 / AD8011ARZ-REEL
AD8011 / AD8011ARZ-REEL7	AD8014 / AD8014ARTZ-REEL7	AD8014 / AD8014ARZ	AD8014 / AD8014ARZ-REEL	AD8014 / AD8014ARZ-REEL7
AD8015 / AD8015ACHIPS	AD8015 / AD8015ARZ	AD8015 / AD8015ARZ-REEL7	AD8017 / AD8017ARZ	AD8017 / AD8017ARZ-REEL
AD8017 / AD8017ARZ-REEL7	AD8031 / AD8031ANZ	AD8031 / AD8031ARTZ-R2	AD8031 / AD8031ARTZ-REEL7	AD8031 / AD8031ARZ
AD8031 / AD8031ARZ-REEL	AD8031 / AD8031ARZ-REEL7	AD8031 / AD8031BNZ	AD8031 / AD8031BRZ	AD8031 / AD8031BRZ-REEL7
AD8031 / AD8031CU-W	AD8032 / AD8032ACHIPS	AD8032 / AD8032ANZ	AD8032 / AD8032ARMZ	AD8032 / AD8032ARMZ-REEL
AD8032 / AD8032ARMZ-REEL7	AD8032 / AD8032ARZ	AD8032 / AD8032ARZ-REEL	AD8032 / AD8032ARZ-REEL7	AD8032 / AD8032BRZ
AD8032 / AD8032BRZ-REEL	AD8032 / AD8032BRZ-REEL7	AD8041 / AD8041ANZ	AD8041 / AD8041ARZ	AD8041 / AD8041ARZ-REEL
AD8041 / AD8041ARZ-REEL7	AD8042 / AD8042ACHIPS	AD8042 / AD8042ARZ	AD8042 / AD8042ARZ-REEL	AD8042 / AD8042ARZ-REEL7
AD8044 / AD8044ANZ	AD8044 / AD8044ARZ-14	AD8044 / AD8044ARZ-14-REEL	AD8044 / AD8044ARZ-14-REEL7	AD8051 / AD8051ARTZ-REEL
AD8051 / AD8051ARTZ-REEL7	AD8051 / AD8051ARZ	AD8051 / AD8051ARZ-REEL	AD8051 / AD8051ARZ-REEL7	AD8052 / AD8052ARMZ
AD8052 / AD8052ARMZ-REEL	AD8052 / AD8052ARMZ-REEL7	AD8052 / AD8052ARZ	AD8052 / AD8052ARZ-REEL	AD8052 / AD8052ARZ-REEL7
AD8054 / AD8054ARUZ	AD8054 / AD8054ARUZ-REEL	AD8054 / AD8054ARUZ-REEL7	AD8054 / AD8054ARZ	AD8054 / AD8054ARZ-REEL
AD8054 / AD8054ARZ-REEL7	AD8056 / AD8056ANZ	AD8056 / AD8056ARMZ	AD8056 / AD8056ARMZ-REEL	AD8056 / AD8056ARMZ-REEL7
AD8056 / AD8056ARZ	AD8056 / AD8056ARZ-REEL	AD8056 / AD8056ARZ-REEL7	AD8057 / AD8057ACHIPS	AD8057 / AD8057ARTZ-REEL
AD8057 / AD8057ARTZ-REEL7	AD8057 / AD8057ARZ	AD8057 / AD8057ARZ-REEL7	AD8091 / AD8091ARTZ-R7	AD8091 / AD8091ARZ
AD8091 / AD8091ARZ-REEL7	AD8092 / AD8092ARMZ	AD8092 / AD8092ARMZ-REEL	AD8092 / AD8092ARMZ-REEL7	AD8092 / AD8092ARZ
AD8092 / AD8092ARZ-REEL	AD8092 / AD8092ARZ-REEL7	AD835 / AD835ANZ	AD835 / AD835ARZ	AD835 / AD835ARZ-REEL
AD835 / AD835ARZ-REEL7	AD8519 / AD8519AKSZ-REEL7	AD8519 / AD8519ARTZ-REEL7	AD8529 / AD8529ARMZ-REEL	AD8529 / AD8529ARZ
AD8529 / AD8529ARZ-REEL	AD8561 / AD8561ANZ	AD8561 / AD8561ARUZ	AD8561 / AD8561ARUZ-REEL	AD8561 / AD8561ARZ
AD8561 / AD8561ARZ-REEL	AD8561 / AD8561ARZ-REEL7	AD8564 / AD8564ARUZ-REEL	AD8564 / AD8564ARZ	AD8564 / AD8564ARZ-REEL
AD8564 / AD8564ARZ-REEL7	MCPCHIPS / AD8031ACHIPS	OP262 / OP262DRUZ-REEL	OP262 / OP262GSZ	OP262 / OP262GSZ-REEL
OP262 / OP262GSZ-REEL7	OP262 / OP262HRUZ	OP262 / OP262HRUZ-REEL	OP262 / OP262TRZ-EP	OP262 / OP262TRZ-EP-R7
OP462 / OP462GSZ	OP462 / OP462GSZ-REEL	OP462 / OP462GSZ-REEL7	OP462 / OP462HRUZ-REEL	

Appendix B - Revision History:			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	31-Mar-2026	03-Jul-2026	Initial Release.



Reliability Report

Report Title: Qualification of ADI Limerick Wafer Fab XFCB Process

Report Number: 25230

Revision: A

Date: 24 March 2026

Summary

This report documents the reliability qualification requirements for the release of the XFCB Processes at Analog Devices Limerick Wafer Fabrication Facility. The products listed below were selected to cover the technology being released.

The AD8032 (dual) is a single-supply voltage feedback amplifier that features high speed performance with 80 MHz of small signal bandwidth, 30 V/µs slew rate and 125 ns settling time. This performance is possible while consuming less than 4.0 mW of power from a single +5 V supply. This feature increases the operation time of high speed, battery-powered systems without compromising dynamic performance. The device is packaged in 8-MINI_SO.

The AD8052 (dual) are low cost, high speed, voltage feedback amplifiers. The amplifiers operate on +3 V, +5 V or ±5 V supplies at low supply current. They have true single-supply capability with an input voltage range extending 200 mV below the negative rail and within 1 V of the positive rail. The device is packaged in 8-SOIC_N-150_MIL.

Die/Fab Product Characteristics

Table 1: Die/Fab Product Characteristics - XFCB at ADI Limerick

Product Characteristics	Product(s) to be qualified	
Generic/Root Part #	AD8032	AD8052
Die Id	8JA17 E	8JA49 D
Die Size (mm)	0.89 x 1.52	0.97 x 1.51
Wafer Fabrication Site	ADI-Limerick	ADI-Limerick
Wafer Fabrication Process	XFCB	XFCB
Die Substrate	Si	Si
Metallization / Layers	AlCu(0.5%) / 2	AlCu(0.5%) / 2
Polyimide	Yes	Yes
Passivation	doped-oxide/SiN	doped-oxide/SiN

Die/Fab Test Results

Table 2: Die/Fab Test Results - XFCB at ADI Limerick

Test Name	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS
High Temperature Operating Life (HTOL)	JESD22-A108	125°C<Tj<135°C, Biased, 1,000 Hours	AD8032	Q21298.1.HO1_RES	0/77
				Q21298.2.HO2_RES	0/77
				Q21298.3.HO3_RES	0/77
			AD8052	Q21299.1.HO1_RES	1[2]/77
				Q21299.2.HO2_RES	0/77
				Q21299.3.HO3_RES	0/77
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	AD8032	Q21298.1.HS1_RES	0/77
			AD8052	Q21299.1.HS1_RES	0/77
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	JESD22-A110	110°C 85%RH 17.7 psia, Biased, 264 Hours	AD8052	Q21299.1.HA1_RES	0/77
				Q21299.2.HA2_RES	0/77
				Q21299.3.HA3_RES	0/77
		130°C 85%RH 33.3 psia, Biased, 96 Hours	AD8032	Q21298.1.HA1_RES	0/77
				Q21298.2.HA2_RES	0/77
				Q21298.3.HA3_RES	0/77
Unbiased HAST (UHST)[1]	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	AD8032	Q21298.1.UH1_RES	0/77
				Q21298.2.UH2_RES	0/77
				Q21298.3.UH3_RES	0/77
			AD8052	Q21299.1.UH1_RES	0/77
				Q21299.2.UH2_RES	0/77
				Q21299.3.UH3_RES	0/77
Temperature Cycling (TC)[1]	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8032	Q21298.1.TC1_RES	0/77
				Q21298.2.TC2_RES	0/77
				Q21298.3.TC3_RES	0/77
			AD8052	Q21299.1.TC1_RES	0/77
				Q21299.2.TC2_RES	0/77
				Q21299.3.TC3_RES	0/77

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.
[2] 1 unit failed at 250 hours HTOL. Refer to FA#292256 / CAPA#2026020301.

Package/Assembly Product Characteristics

Table 3.1: Package/Assembly Product Characteristics - 8-MINI_SO at CARSEM (CRM)

Product Characteristics	Product(s) to be qualified
Generic/Root Part #	AD8032
Package	8-MINI_SO
Body Size (mm)	3.00 x 3.00 x 0.85
Assembly Location	CARSEM (CRM)
MSL/Peak Reflow Temperature(°C)	1 / 260°C
Mold Compound	Hitachi CEL 8240HF10LXC
Die Attach	Hysol QMI 519 conductive
Leadframe Material	Copper
Lead Finish	100Sn
Wire Bond Material/Diameter (mils)	Tanaka GLD 4N Gold / 1.00

Table 3.2: Package/Assembly Product Characteristics - 8-SOIC_N at CARSEM (CRM)

Product Characteristics	Product(s) to be qualified
Generic/Root Part #	AD8052
Package	8-SOIC_N
Body Size (mm)	5.00 x 4.00 x 1.5
Assembly Location	CARSEM (CRM)
MSL/Peak Reflow Temperature(°C)	1 / 260°C
Mold Compound	Sumitomo 6600H
Die Attach	Ablestik 84-1 LMISR4 conductive
Leadframe Material	Copper
Lead Finish	100Sn
Wire Bond Material/Diameter (mils)	Tanaka M3 4N Gold / 1.30

Package/Assembly Test Results

Table 4.1: Package/Assembly Test Results - 8-MINI_SO at CARSEM (CRM)

Test Name	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS
Solder Heat Resistance (SHR)	J-STD-020	MSL-1	AD8032	Q21298.1.SH1_RES	0/16
				Q21298.2.SH2_RES	0/16
				Q21298.3.SH3_RES	0/16
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	JESD22-A110	130°C 85%RH 33.3 psia, Biased, 96 Hours	AD8032	Q21298.1.HA1_RES	0/77
				Q21298.3.HA2_RES	0/77
				Q21298.1.HA3_RES	0/77
Unbiased HAST (UHST) [1]	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	AD8032	Q21298.1.UH1_RES	0/77
				Q21298.2.UH2_RES	0/77
				Q21298.3.UH3_RES	0/77
Temperature Cycling (TC)[1]	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8032	Q21298.1.TC1_RES	0/77
				Q21298.2.TC2_RES	0/77
				Q21298.3.TC3_RES	0/77
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	AD8032	Q21298.1.HS1_RES	0/77

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

Table 4.2: Package/Assembly Test Results - 8-SOIC_N at CARSEM (CRM)

Test Name	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS
Solder Heat Resistance (SHR)	J-STD-020	MSL-1	AD8052	Q21299.1.SH1_RES	0/16
				Q21299.2.SH2_RES	0/16
				Q21299.3.SH3_RES	0/16
Highly Accelerated Temperature and Humidity Stress Test (HAST)[1]	JESD22-A110	110°C 85%RH 17.7 psia, Biased, 264 Hours	AD8052	Q21299.1.HA1_RES	0/77
				Q21299.2.HA2_RES	0/77
				Q21299.3.HA1_RES	0/77
Unbiased HAST (UHST) [1]	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	AD8052	Q21299.1.UH1_RES	0/77
				Q21299.2.UH2_RES	0/77
				Q21299.3.UH3_RES	0/77
Temperature Cycling (TC)[1]	JESD22-A104	-65°C/+150°C, 500 Cycles	AD8052	Q21299.1.TC1_RES	0/77
				Q21299.2.TC2_RES	0/77
				Q21299.3.TC3_RES	0/77
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	AD8052	Q21299.1.HS1_RES	0/77

[1] These samples were subjected to preconditioning at MSL 1 with 3x reflow peak temp of 260°C prior to the start of the stress test.

ESD and Latch-Up Test Results

Table 5: ESD Test Result

ESD Model	Generic/Root Part #	Package	ESD Test Spec	RC Network	Highest Pass Level	Class
FICDM	AD8032	8-MINI_SO	JS-002	1Ω, Cpkg	±1250V	C3
FICDM	AD8052	8-SOIC_N	JS-002	1Ω, Cpkg	±1250V	C3
HBM	AD8032	8-MINI_SO	JS-001	1.5kΩ, 100pF	±1500V	1C
HBM	AD8052	8-SOIC_N	JS-001	1.5kΩ, 100pF	±1500V	1C

Table 6: Latch Up Test Result

LU Test Spec	Generic/Root Part #	Passing Current	Passing Over-Voltage	Temperature (T_A)	Class
JESD78	AD8032	+200mA, -200mA	+/- 9V	25°C	I
JESD78	AD8052	+200mA, -200mA	+/- 7.5V	25°C	I

Approvals

Reliability Engineer: